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**HASUMI et al.**(10) **Pub. No.: US 2023/0230870 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **WAFER PROCESSING SHEET AND WAFER  
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**ABSTRACT**

A sheet for processing a wafer, including a substrate sheet that comes into contact with a main surface of the wafer, wherein the substrate sheet has an exponential coefficient in an exponential trendline for storage modulus  $E'_{30-80}$  at 30° C. to 80° C. of  $-0.035$  to  $-0.070$ .

